

**Amendments to the Specification:**

Please replace the paragraph beginning at page 16, line 5 with the following rewritten paragraph:

Figure 17 represents an embodiment of the overcurrent and overvoltage protection device shown schematically in Figure 14. Thus, it further includes a third thyristor element 734 mounted upon an associated integrally-formed bond pad and connector piece 732. In this case, the bottom-facing surface of the thyristor element 734 (one of the cathode or anode) will be electrically connected to the bottom-facing surfaces of both thyristor elements 726, 730 via, for example, another electrical line in the associated printed circuit board. The opposite side of the thyristor element 734 (i.e., either the anode or cathode) is bonded to the integrally formed bond pad and connector piece 732 which, in turn, will serve as Terminal C of the device. Alternatively, ~~thyristors~~ thyristor elements 726, 730, 734 could be mounted on a single die pad 731 as opposed to their respective integrally-formed bond pad and connector pieces 724, 728, 732. Such bond pad 731 would provide the common electrical connection point between the three ~~thyristors~~ thyristor elements 726, 730, 734. Thereafter, upon placement of the overcurrent and overvoltage protection device upon a printed circuit board, bottom side down, the respective bottom surfaces of thyristor elements 726, 730, 734 would come in contact with a surface of the associated printed circuit board whereupon, via electrical lines formed in the printed circuit board, for example, thyristor element 726 would be electrically connected to Terminal B, thyristor element 730 would be electrically connected to Terminal E, and thyristor element 734 would be electrically connected to Terminal C.

Please replace the paragraph beginning at page 17, line 6 with the following rewritten paragraph:

Figures 21 and 22 offer alternative terminal configurations with respect to the multiple thyristor embodiments of the present invention discussed with reference to Figures 13 and 14. As shown in Figure 21, multiple terminals 750, 752, 754, 756 and 758 may be formed at various edge areas of an associated substrate 610. Indeed, as shown in Figure 22, such terminals ~~760, 762, 764, 766 and 768~~750, 752, 754, 756 and 758 could well be formed at any or all of the four side edges of the associated substrate 610.